# 晶片鋁墊與打線腳位對應表

## Pad Location Information

| ***Product Description*** | |
|---|---|
| ***Device Name*** | __GDS6606ACP6__ |
| ***Mask ID*** | ___BK2046A*__ ( ***代表 A-Z 共用版本,僅適用在 Pad 位置相同**** ) |
| ***Requirement*** | ☐ Tapeout 前 try bonding(封裝廠僅評估能否拉線)<br>☒ Tapeout 後 ENG bonding diagram(封裝廠須出 BD 圖) |
| ***Package Type & Size***<br>***Material type*** | Package Type: CPC - 20 L *( ___ x ___ x _____ 膠體厚度) *L/F Pin Pitch: __<br>L/F Pad Size: ____ x ____ ( SOP / TSOP / TSSOP / MSOP: ☐ Normal ☐Exposed )<br>Compound: Green |
| ***Die Size*** | 1490 μm × 1520 μm ( Scribe Line: 60 μm) |
| ***Wafer Size*** | 8 Inch |
| ***Material Description*** | |
| ***Wafer Substrate*** | ☒ P-Sub ☐ N-Sub |
| ***Die Bond Material*** | ☒ Conductive ☐ **Non-conductive** ☐ Other: |
| ***Wire*** | ☐ Au 1.0mil ☐ Cu 1.0mil<br>☒ Other: _Cu 0.8_mil (備註: ) |
| ***Metal Layer*** | Total 4 layer, Top metal thickness: _3.2(ThinM4/M3/M2)_ um |
| ***Circuit under bond pad*** | ☐ No ☒ Yes |
| ***Foundry*** | FAB: SKHynix |
| ***Metallization*** | Al_98_% & Cu_1.5_% & Si_0.5_% |
| ***Specially Bonding Note*** | |

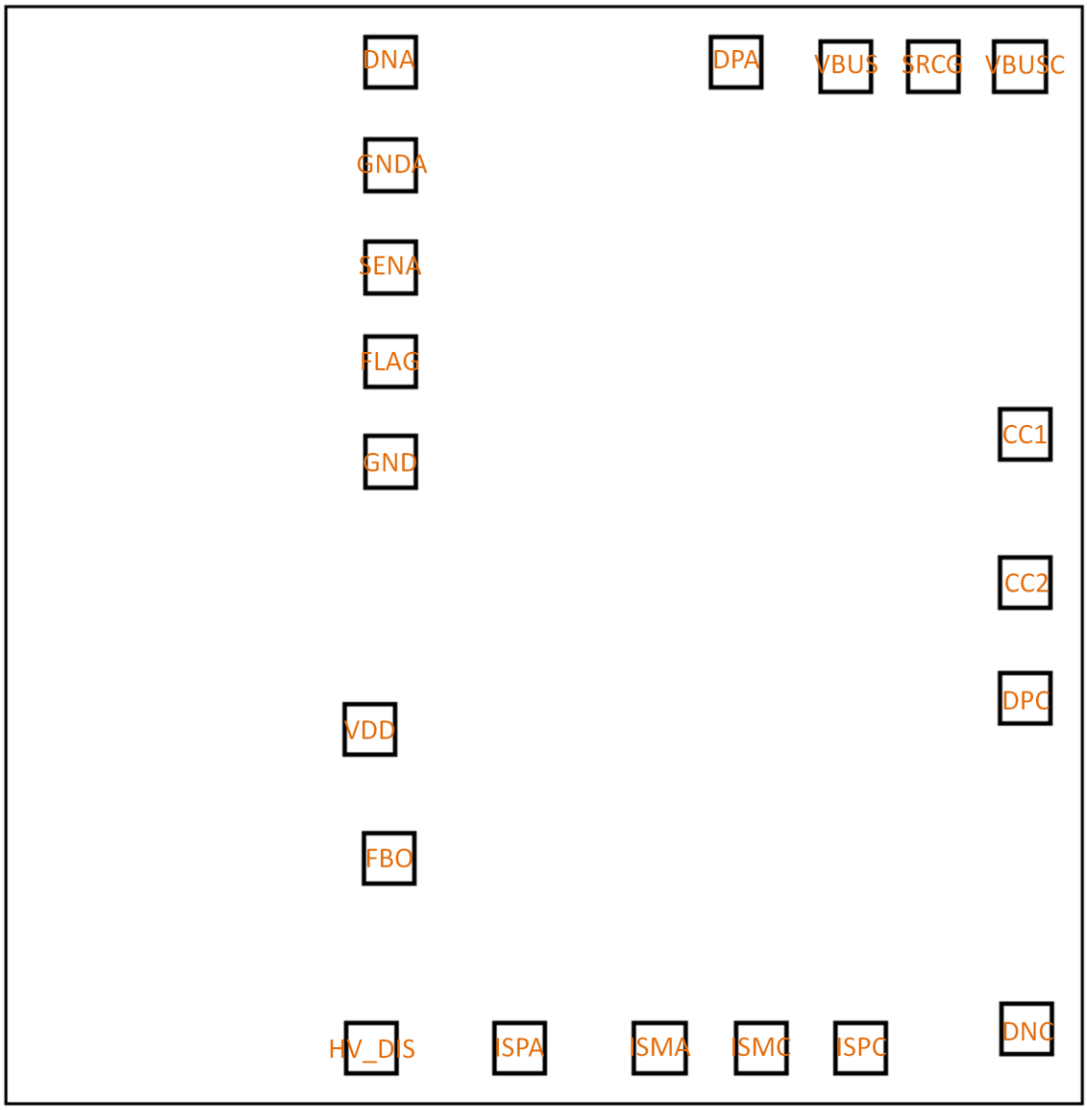
Unit : um

| *Bond Pad Name* | *Ball Center (X,Y)* | *Pad Center (X,Y)* | *Pad Size (X,Y)* | *L/F Pin Out Number* | *Bond Pad Name* | *Ball Center (X,Y)* | *Pad Center (X,Y)* | *Pad Size (X,Y)* | *L/F Pin Out Number* |
|---|---|---|---|---|---|---|---|---|---|
| GNDA | | (-212.6,540.7) | (70,70) | 3 | ISPC | | (436.5,-681.3) | (70,70) | 13 |
| SENA | | (-212.6,399) | (70,70) | 4 | DNC | | (666.3,-654.3) | (70,70) | 14 |
| FLAG | | (-213.2,269.2) | (70,70) | 5 | DPC | | (664.3,-196.8) | (70,70) | 15 |
| GND | | (-213.2,130.4) | (70,70) | 6 | CC2 | | (664.3,-37.1) | (70,70) | 16 |
| VDD | | (-242.5,-239.3) | (70,70) | 7 | CC1 | | (664.3,168.5) | (70,70) | 17 |
| FBO | | (-215.6,-418.6) | (70,70) | 8 | VBUSC | | (657.5,677.4) | (70,70) | 18 |
| HV_DIS | | (-239.6,-681.3) | (70,70) | 9 | SRCG | | (537.1,677.4) | (70,70) | 19 |
| ISPA | | (-34.5,-681.3) | (70,70) | 10 | VBUS | | (416.8,677.4) | (70,70) | 20 |
| ISMA | | (159,-681.3) | (70,70) | 11 | DPA | | (264.5,682.3) | (70,70) | 1 |

| | | | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|
| ISMC | | (298.8,-681.3) | (70,70) | 12 | DNA | | (-212.6,682.3) | (70,70) | 2 |
| | | | | | | | | | |

## ***Bond Pad LAYOUT of Chip***

附件一



# *Brief 打線示意圖*

附件二